

N-MOSFET 60V 1.7mΩ 100A

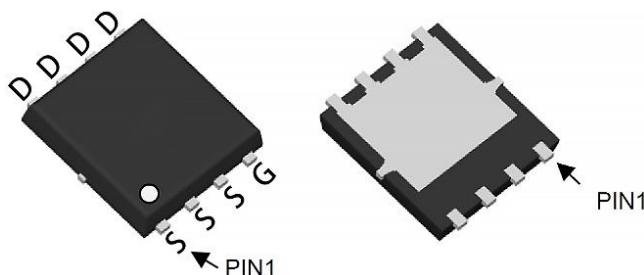
■ Product Summary

- VDS 60V
- ID 100A
- RDS(ON) (at VGS=10V) <2.1 mΩ (Typ: 1.7 mΩ)

■ Naming convention

M	G	C	0	1	7	N	0	6	A	L
Megain		B: PDFN3X3 C: PDFNSX6 P: TO220 H: TO263 S: SOP8 D: TO252	RDS(ON) Typ. @VGS=10V	N: N P: P C: N+P D: N+N	10: 100V 08: 80V 06: 60V 04: 40V 03: 30V	10: 100V 08: 80V 06: 60V 04: 40V 03: 30V	A: VGS 20/-12 w/o A: VGS±20	L: VIn(1~2.5V) N: VIn(2~4V)		

■ Pin configuration



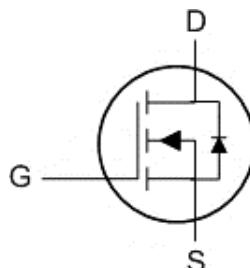
■ Features

- Advanced Trench MOS Technology
- Low Gate Charge
- Low RDS(ON)
- 100% EAS Guaranteed
- Green Device Available

■ Application

- Motor Control
- DC/DC Converter.
- Synchronous rectifier applications

■ Symbol



■ Ordering Information

Order code	Package	Form	Quantity (PCS)	Marking
MGC017N06L	PDFN 5x6	Tape & Reel	5000 / Tape & Reel	MGC017N06L

■ Absolute Maximum Ratings

Tc=25°C Unless Otherwise Noted.

Symbol	Parameter	Value	Units
Vds	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
Id	Drain Current – Continuous ^{1,6} (Tc=25°C)	100	A
	Drain Current – Continuous ^{1,6} (Tc=100°C)	66	A
Idm	Pulsed Drain Current ²	400	A
EAS	Single Pulse Avalanche Energy ³	306	mJ
Ias	Avalanche Current	35	A
Pd	Total Power Dissipation ⁴ (Tc=25°C)	83	W
Tstg	Storage Temperature Range	-55 to 150	°C
Tj	Operating Junction Temperature Range	-55 to 150	°C

■ Thermal Characteristics

Symbol	Parameter	Max	Units
R _{0JA}	Thermal Resistance Junction to Ambient ¹	55	°C/W
R _{0JC}	Thermal Resistance Junction to Case ¹	1.1	°C/W

■ Electrical Characteristics

T_J=25°C Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
B _{VDS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
R _{DSON}	Drain-Source On-state Resistance ²	V _{GS} =10V, I _D =20A	-	1.7	2.1	mΩ
		V _{GS} =4.5V, I _D =20A		2.3	3.2	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	1.2	-	2.3	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =52V, V _{GS} =0V	-	-	1	uA
		V _{DS} =52V, V _{GS} =0V T _J =55°C	-	-	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
g _{fS}	Forward Transconductance	V _{DS} =5V, I _D =20A	-	60	-	S
R _G	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	-	1.6	-	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =30V, V _{GS} =10V I _D =20A	-	102	-	nC
Q _g	Total Gate Charge (4.5V)		-	54.1	-	
Q _{gs}	Gate-Source Charge		-	15.7	-	
Q _{gd}	Gate-Drain Charge		-	27.9	-	
T _{d(ON)}	Turn-on Delay Time	V _{DS} =30V, V _{GS} =10V, R _G =3Ω, I _D =20A	-	15	-	nS
T _r	Turn-on Rise Time		-	12	-	
T _{d(OFF)}	Turn-off Delay Time		-	60	-	
T _f	Turn-off Fall Time		-	19	-	
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, F=1MHz	-	5471	-	pF
C _{oss}	Output Capacitance		-	1847	-	
C _{rss}	Reverse Transfer Capacitance		-	86	-	
Diode Characteristics						
I _s	Continuous Source Current ^{1,5,6}	V _G =V _D =0V, Force Current	-	-	100	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _s =1A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI _F /dt=100A/us	-	50	-	nS
Q _{rr}	Reverse Recovery Charge		-	72	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,V_{GS}=10V,L=0.5mH,I_{AS}=35A.
- 4.The power dissipation is limited by 150°C junction temperature.
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

■ Typical Characteristics

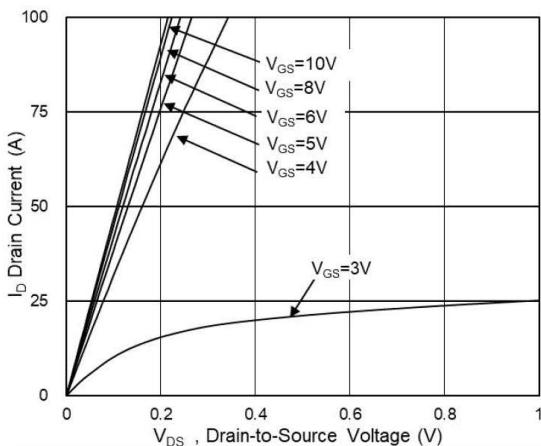


Fig.1 Typical Output Characteristics

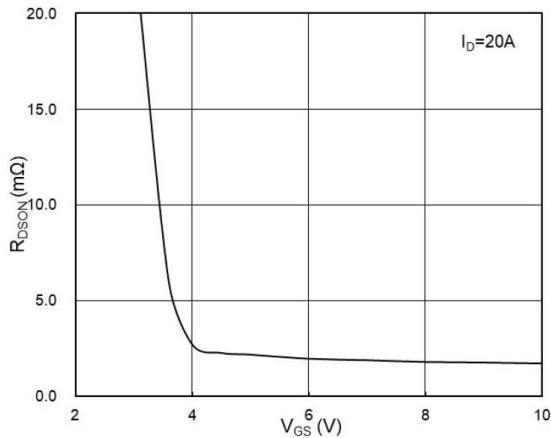


Fig.2 On-Resistance vs G-S Voltage

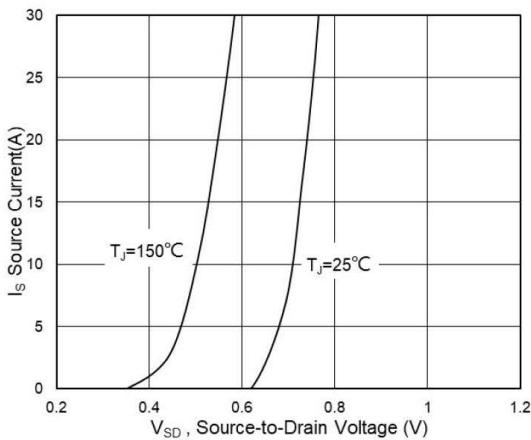


Fig.3 Diode Forward Voltage vs Current

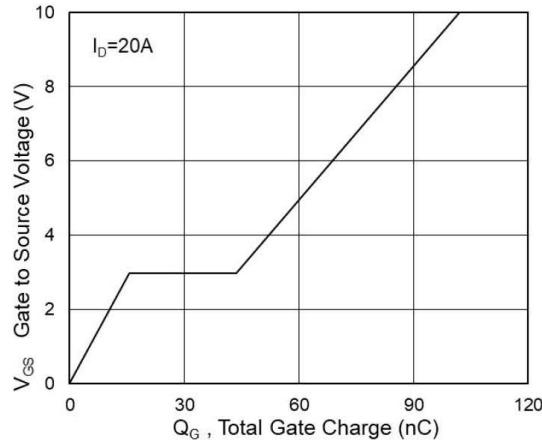


Fig.4 Gate-Charge Characteristics

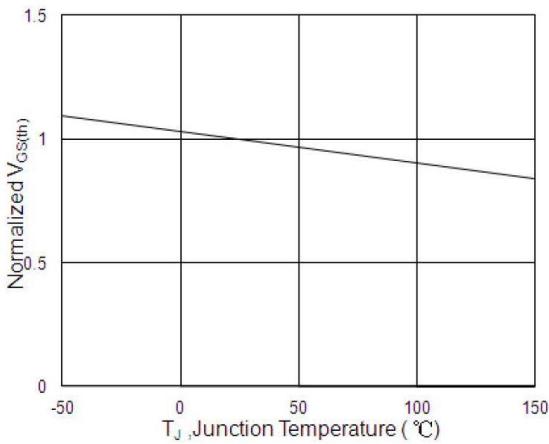


Fig.5 Normalized $V_{GS(th)}$ vs T_J

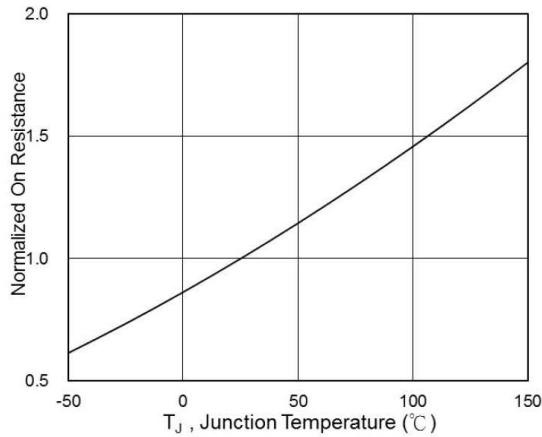


Fig.6 Normalized $R_{DS(on)}$ vs T_J

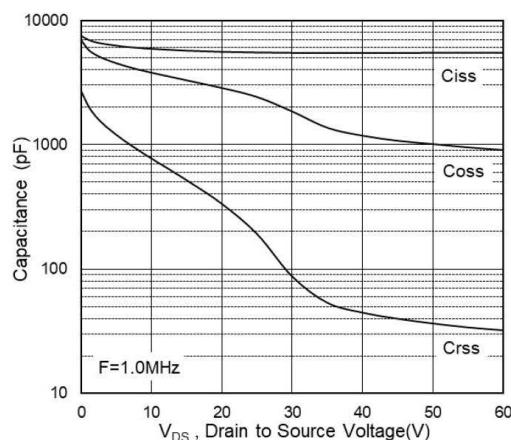


Fig.7 Capacitance

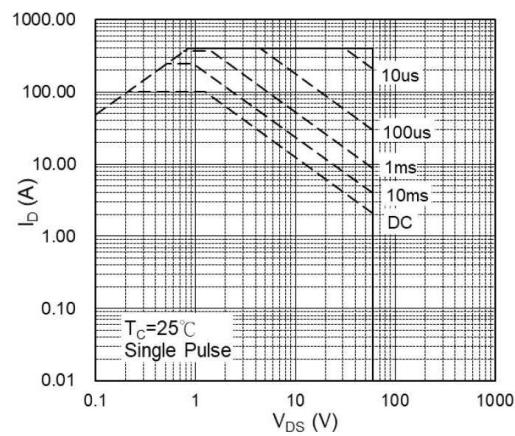


Fig.8 Safe Operating Area

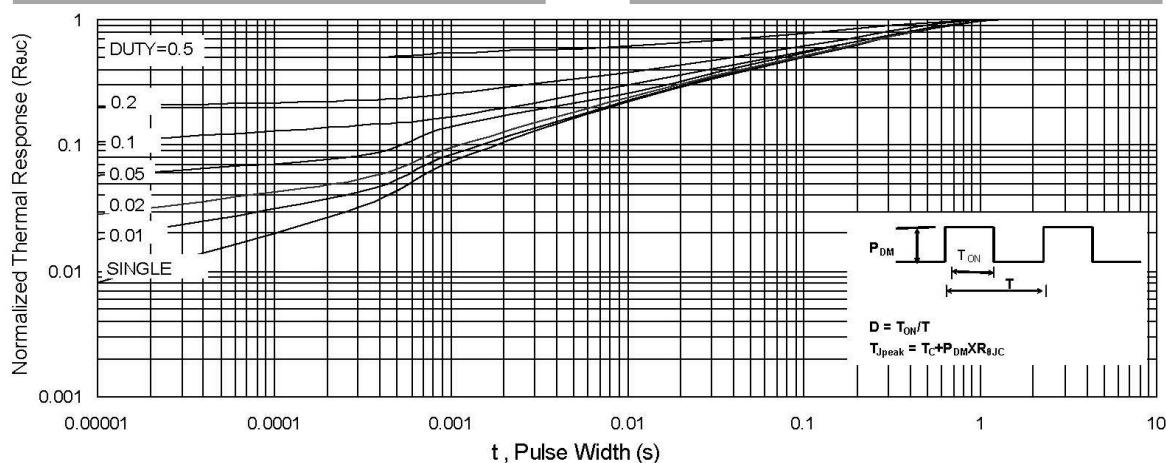


Fig.9 Normalized Maximum Transient Thermal Impedance

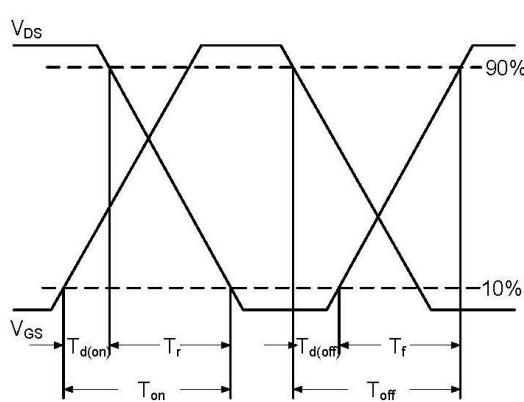


Fig.10 Switching Time Waveform

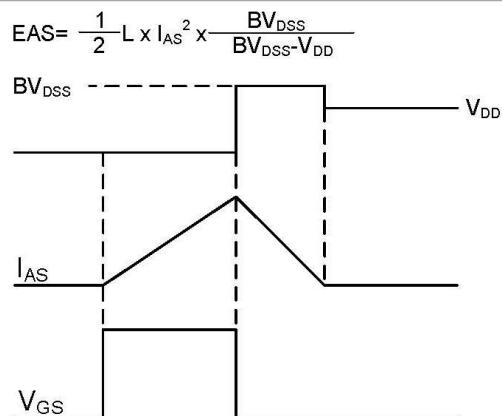
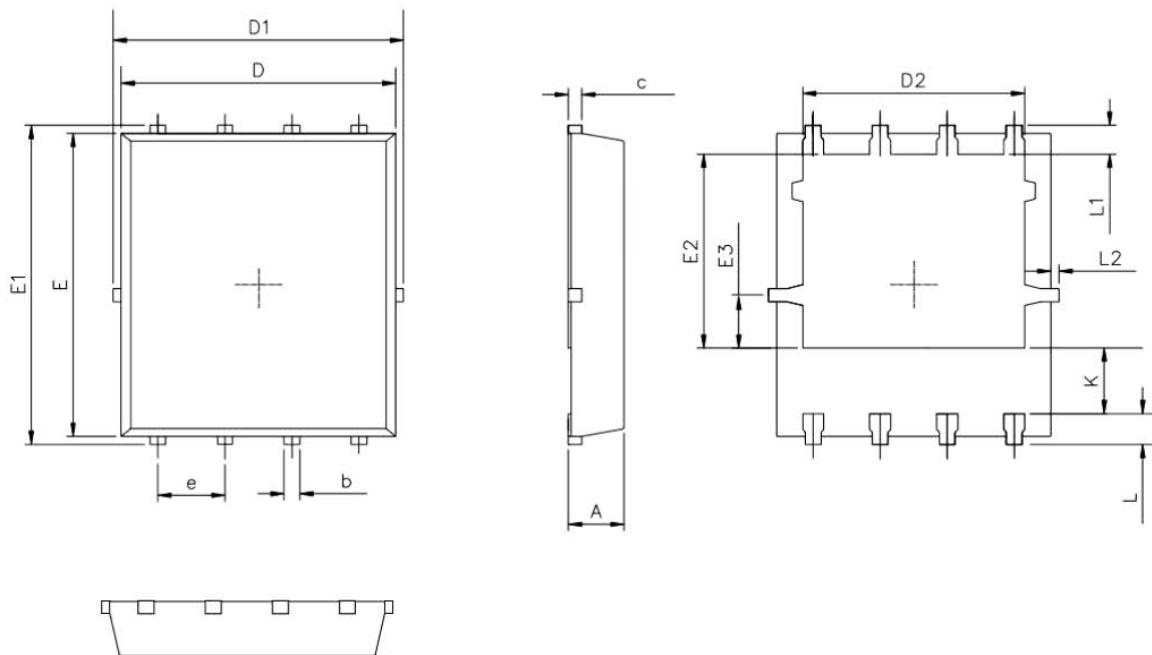


Fig.11 Unclamped Inductive Switching Waveform

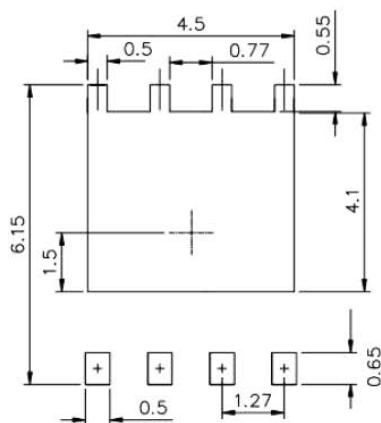
■ Package size

Unit: mm.

PDFN 5X6:



RECOMMENDED LAND PATTERN



UNIT:mm

	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.35	0.50
c	0.10	0.20	0.30
D	4.80	5.00	5.30
D1	4.90	5.10	5.50
D2	3.92	4.02	4.20
E	5.65	5.75	5.85
E1	5.90	6.05	6.20
E2	3.325	3.525	3.775
E3	0.80	0.90	1.00
e		1.27	
L	0.40	0.55	0.70
L1		0.65	
L2	0.00		0.15
K	1.00	1.30	1.50